

CMi introduces a unified naming policy for the coating and development equipment (EVG150, ACS200, RT88)

Important: for coating recipes, the standard cleaning step is "EC", i.e. edge clean with back-side rinse option ON. "EBR" is only used with mask-aligners in vacuum contact mode. "N" is only used when coating PR on both sides.

Recipe Type	Wafer Size	Thermal treatment / Preparation	Photoresist type	Thickness [um]	Cleaning Step / Details
C	4	H	1512	1u1	EBR
D	6	D	3007	u6	EC
B	-	DH	3027	3u	N
S	-	LOR	10XT	15u	SP
M	-	BARC	40XT	20u	PUD
	-	PEB	nLOF	1u4	B
	-	SB	LOR	u4	STRIP
	-	HB	108Y	u45	EBR
	-	RF	35G	1u2	EC
	-	PEB			
		N			

Explanation:

C = COATING
D = DEVELOPMENT
B = BAKE only
S = SOLVENT only
M = PM/Maintenance

4 inch
6 inch

H = HMDS
D = DEHYDRATE
DH = DEHY+HMDS
LOR = LOR 5A coat.
BARC = DUV42P coat.
PEB = Post Exp. Bake
SB = Soft bake
HB = Hard bake
RF = Reflow
PEB
N = None

Format XuY

EBR = edge bead removal
EC = edge clean + back rinse
N = NONE (noBSR)
SP = SPRAY
PUD = PUDDLE
B = SPRAY + PUDDLE
Stripping
EBR only
EC/BSR only